

# Specification Sheet

## Gold Tin Solder Paste

(AuSn, Purity: 99.9%, APS: 80-100nm)

Stock No: NS6130-01-157, CAS: 7440-57-5/7440-31-5

### Product Indication

Indication	:	NS6130-01-157
Alloy	:	Sn20/Au80 (Standard), Sn25/Au75 (upon request), Other alloys are available on request

### Physical Properties

Particle Size	:	80-100nm
Shape	:	Spherical
Melting Point	:	Sn20/Au80 = 280°C, Sn25/Au75 = 280°C
Composition	:	Sn20/Au80
Density	:	Sn20/Au80 = 7.4 g/cc, Sn25/Au75 = 7.4 g/cc

### Solder Paste

Metal Content	:	Standard 89% ± 1%
Viscosity Range	:	130 ± 40 Pas, Physica CSS 10 s-1
Density	:	3.99 ± 0.2 g/ml

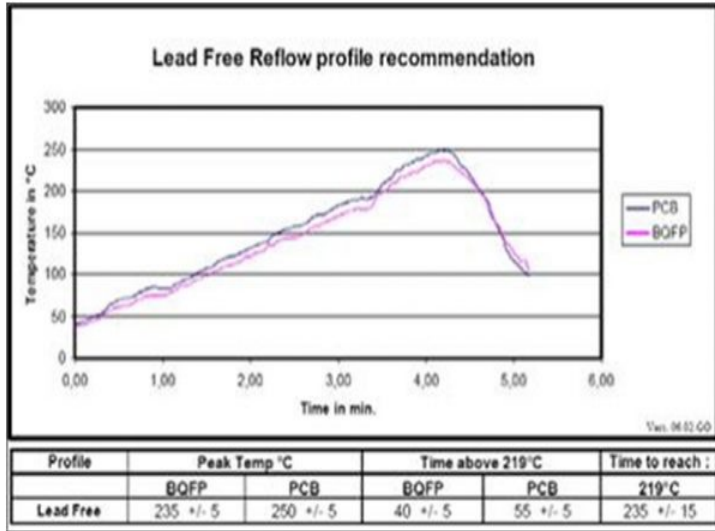
### Performance Properties

Typical Print Thickness	:	0.4 – 0.65 mm pitch: 150 microns, < 0.4 mm pitch: 120 microns
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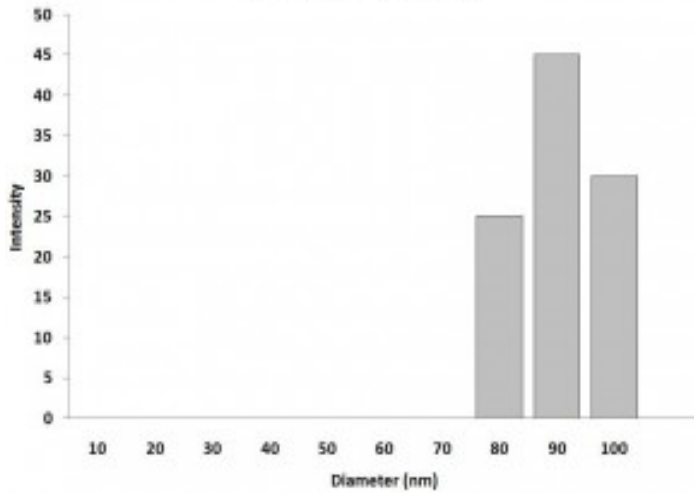
**Main Inspect Verifier** : **Manager QC**

**Note:** Product Specification are subject to amendment and may change over time

## Characterization of Gold Tin Solder Paste



### Lead Free Reflow profile



### Particles Size Analysis - Gold Tin Solder Paste